



ITW

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST-CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON December 8, 2005.

Depositor: John A. Jordan

John A. Jordan 12/8/05
(Signature and Date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of : December 8, 2005
John H. Magerlein, et al. : Examiner: N/A
Confirmation No.: 2811
Serial No.: 10/771,817 : Art Unit: 3965
Filed: June 16, 2004 : IBM Corporation
Intellectual Property Law
Dept. 1Q0A/040-3, 1701 North Street
Endicott, New York 13760
Title: METHOD OF MANUFACTURE OF
SILICON BASED PACKAGE AND
DEVICES MANUFACTURED
THEREBY :

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The status of the above-identified application, Serial No. 10/771,817 filed on June 16, 2004, is requested.

Respectfully submitted,

John H. Magerlein, et al.

By:

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WHS/JAJ

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